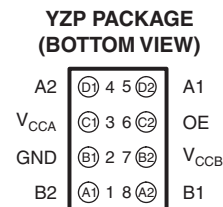
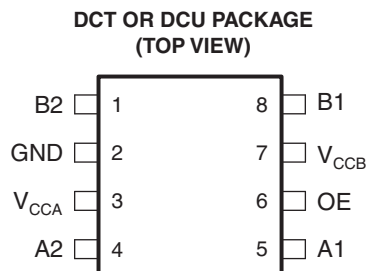


FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- 1.65 V to 3.6 V on A port and 2.3 V to 5.5 V on B port ($V_{CCA} \leq V_{CCB}$)
- V_{CC} Isolation Feature – If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - A Port
 - 2500-V Human-Body Model (A114-B)
 - 250-V Machine Model (A115-A)
 - 1500-V Charged-Device Model (C101)
 - B Port
 - 8-kV Human-Body Model (A114-B)
 - 250-V Machine Model (A115-A)
 - 1500-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

This two-bit noninverting translator uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.65 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCA} must be less than or equal to V_{CCB} . V_{CCB} accepts any supply voltage from 2.3 V to 5.5 V. This allows for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

ORDERING INFORMATION

| T_A | PACKAGE ⁽¹⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING ⁽²⁾ |
|---------------|--|--------------|-----------------------|---------------------------------|
| –40°C to 85°C | NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP | Reel of 3000 | TXS0102YZPR | |
| | SSOP – DCT | Reel of 3000 | TXS0102DCTR | NFEZ_ _ _ |
| | | Tube of 250 | TXS0102DCTT | NFEZ_ _ _ |
| | VSSOP – DCU | Reel of 3000 | TXS0102DCUR | _ _ NFE |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.
DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

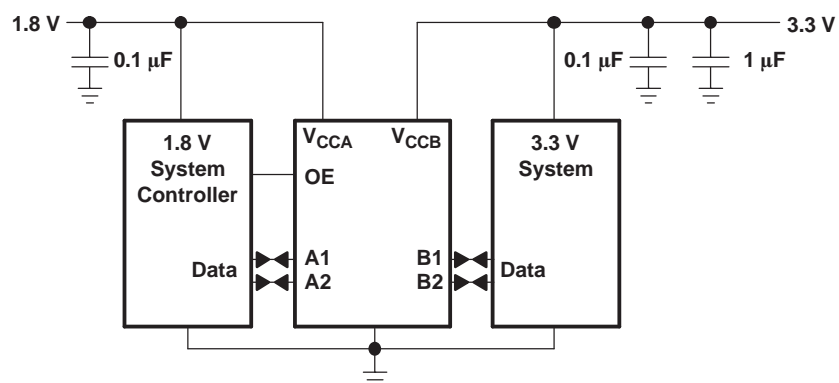
TXS0102 2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

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PIN DESCRIPTION (DCT AND DCU PACKAGES)

| NO. | NAME | FUNCTION |
|-----|-----------|---|
| 1 | B2 | Input/output B. Referenced to V_{CCB} . |
| 2 | GND | Ground |
| 3 | V_{CCA} | A-port supply voltage. $1.65\text{ V} \leq V_{CCA} \leq 3.6\text{ V}$ and $V_{CCA} \leq V_{CCB}$ |
| 4 | A2 | Input/output A. Referenced to V_{CCA} . |
| 5 | A1 | Input/output A. Referenced to V_{CCA} . |
| 6 | OE | 3-state output mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA} . |
| 7 | V_{CCB} | B-port supply voltage. $2.3\text{ V} \leq V_{CCB} \leq 5.5\text{ V}$ |
| 8 | B1 | Input/output B. Referenced to V_{CCB} . |

TYPICAL OPERATING CIRCUIT



Absolute Maximum Ratings⁽¹⁾

over recommended operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---------------|---|-------------|------|-----------------|------|
| V_{CCA} | Supply voltage range | | -0.5 | 4.6 | V |
| V_{CCB} | Supply voltage range | | -0.5 | 6.5 | V |
| V_I | Input voltage range ⁽²⁾ | A port | -0.5 | 4.6 | V |
| | | B port | -0.5 | 6.5 | |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | A port | -0.5 | 4.6 | V |
| | | B port | -0.5 | 6.5 | |
| V_O | Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾ | A port | -0.5 | $V_{CCA} + 0.5$ | V |
| | | B port | -0.5 | $V_{CCB} + 0.5$ | |
| I_{IK} | Input clamp current | $V_I < 0$ | | -50 | mA |
| I_{OK} | Output clamp current | $V_O < 0$ | | -50 | mA |
| I_O | Continuous output current | | | ±50 | mA |
| | Continuous current through V_{CCA} , V_{CCB} , or GND | | | ±100 | mA |
| θ_{JA} | Package thermal impedance ⁽⁴⁾ | DCT package | | 220 | °C/W |
| | | DCU package | | 227 | |
| | | YZP package | | 102 | |
| T_{stg} | Storage temperature range | | -65 | 150 | °C |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

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Recommended Operating Conditions⁽¹⁾⁽²⁾

| | | V_{CCA} | V_{CCB} | MIN | MAX | UNIT | |
|---------------------|------------------------------------|--------------------------------|------------------------------------|----------------|-----------------|-----------------------|------|
| V_{CCA} | Supply voltage ⁽³⁾ | | | 1.65 | 3.6 | V | |
| V_{CCB} | | | | 2.3 | 5.5 | | |
| V_{IH} | High-level input voltage | A-port I/Os | 1.65 V to 1.95 V 2.3 V to 3.6 V | 2.3 V to 5.5 V | $V_{CCI} - 0.2$ | V_{CCI} | V |
| | | | | | $V_{CCI} - 0.4$ | V_{CCI} | |
| | | B-port I/Os | 1.65 V to 3.6 V | 2.3 V to 5.5 V | $V_{CCI} - 0.4$ | V_{CCI} | |
| OE input | $V_{CCA} \times 0.65$ | 5.5 | | | | | |
| V_{IL} | Low-level input voltage | A-port I/Os | 1.65 V to 3.6 V | 2.3 V to 5.5 V | 0 | 0.15 | V |
| | | B-port I/Os | | | 0 | 0.15 | |
| | | OE input | | | 0 | $V_{CCA} \times 0.35$ | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | A-port I/Os, push-pull driving | 1.65 V to 3.6 V | 2.3 V to 5.5 V | | 10 | ns/V |
| | | B-port I/Os, push-pull driving | | | | 10 | |
| | | Control input | | | | 10 | |
| T_A | Operating free-air temperature | | | -40 | 85 | °C | |

- (1) V_{CCI} is the supply voltage associated with the input port.
(2) V_{CCO} is the supply voltage associated with the output port.
(3) V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.

Electrical Characteristics⁽¹⁾⁽²⁾⁽³⁾

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CCA} | V _{CCB} | T _A = 25°C | | | –40°C to 85°C | | UNIT |
|-------------------------------------|---|----------------------------|------------------|-----------------------|-----|-----|-------------------------|------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | |
| V _{OHA} | I _{OH} = –20 μA, V _{IB} ≥ V _{CCB} – 0.4 V | 1.65 V to 3.6 V | 2.3 V to 5.5 V | | | | V _{CCA} × 0.67 | | V |
| V _{OLA} | I _{OL} = 1 mA, V _{IB} ≤ 0.15 V | 1.65 V to 3.6 V | 2.3 V to 5.5 V | | | | 0.4 | | V |
| V _{OHB} | I _{OH} = –20 μA, V _{IA} ≥ V _{CCA} – 0.2 V | 1.65 V to 3.6 V | 2.3 V to 5.5 V | | | | V _{CCB} × 0.67 | | V |
| V _{OLB} | I _{OL} = 1 mA, V _{IA} ≤ 0.15 V | 1.65 V to 3.6 V | 2.3 V to 5.5 V | | | | 0.4 | | V |
| I _I | OE | 1.65 V to 5.5 V | 1.65 V to 5.5 V | | | ±1 | | ±2 | μA |
| I _{off} | A port | 0 V | 0 to 5.5 V | | | ±1 | | ±2 | μA |
| | B port | 0 to 3.6 V | 0 V | | | ±1 | | ±2 | μA |
| I _{OZ} | A or B port | 1.65 V to 5.5 V | 2.3 V to 5.5 V | | | ±1 | | ±2 | μA |
| I _{CCA} | V _I = V _O = open, I _O = 0 | 1.65 V to V _{CCB} | 2.3 V to 5.5 V | | | | | 2.4 | μA |
| | | 3.6 V | 0 V | | | | | 2.2 | |
| | | 0 V | 5.5 V | | | | | –1 | |
| I _{CCB} | V _I = V _O = open, I _O = 0 | 1.65 V to V _{CCB} | 2.3 V to 5.5 V | | | | | 12 | μA |
| | | 3.6 V | 0 V | | | | | –1 | |
| | | 0 V | 5.5 V | | | | | 1 | |
| I _{CCA} + I _{CCB} | V _I = V _{CCI} or GND, I _O = 0 | 1.65 V to V _{CCB} | 2.3 V to 5.5 V | | | | | 14.4 | μA |
| C _I | OE | 3.3 V | 3.3 V | | | 2.5 | | 3.5 | pF |
| C _{io} | A or B port | 3.3 V | 3.3 V | | | 10 | | | pF |
| | A port | | | | | 5 | | 6 | |
| | B port | | | | | 6 | | 7.5 | |

 (1) V_{CCI} is the V_{CC} associated with the input port.

 (2) V_{CCO} is the V_{CC} associated with the output port.

 (3) V_{CCA} must be less than or equal to V_{CCB}, and V_{CCA} must not exceed 3.6 V.

Timing Requirements

 over recommended operating free-air temperature range, V_{CCA} = 1.8 V ± 0.15 V (unless otherwise noted)

| | | V _{CCB} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | UNIT |
|----------------|--------------------|-------------------------------------|-----|------------------------------------|-----|----------------------------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| Data rate | Push-pull driving | 21 | | 22 | | 24 | | Mbps |
| | Open-drain driving | 1 | | 1 | | 1 | | |
| t _w | Push-pull driving | Data inputs | 47 | 45 | 41 | | | ns |
| | Open-drain driving | | 500 | 500 | 500 | | | |

Timing Requirements

 over recommended operating free-air temperature range, V_{CCA} = 2.5 V ± 0.2 V (unless otherwise noted)

| | | V _{CCB} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | | UNIT |
|----------------|--------------------|-------------------------------------|-----|------------------------------------|-----|----------------------------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| Data rate | Push-pull driving | 20 | | 22 | | 24 | | Mbps |
| | Open-drain driving | 1 | | 1 | | 1 | | |
| t _w | Push-pull driving | Data inputs | 50 | 45 | 41 | | | ns |
| | Open-drain driving | | 500 | 500 | 500 | | | |

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2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

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Timing Requirements

over recommended operating free-air temperature range, $V_{CCA} = 3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

| | | $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|-----------|--------------------|--|--------------------|--|-----|------|
| | | MIN | MAX | MIN | MAX | |
| Data rate | Push-pull driving | 23 | | 24 | | Mbps |
| | Open-drain driving | 1 | | 1 | | |
| t_w | Pulse duration | Data inputs | Push-pull driving | 43 | 41 | ns |
| | | | Open-drain driving | 500 | 500 | |

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (unless otherwise noted)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | $V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$ | | $V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|---------------|-------------------------|-------------|--------------------|---|------|---|------|---|------|------|
| | | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PHL} | A | B | Push-pull driving | 5.3 | | 5.4 | | 6.8 | | ns |
| | | | Open-drain driving | 2.3 | 8.8 | 2.4 | 9.6 | 2.6 | 10 | |
| t_{PLH} | | | Push-pull driving | 6.8 | | 7.1 | | 7.5 | | |
| | | | Open-drain driving | 45 | 260 | 36 | 208 | 27 | 198 | |
| t_{PHL} | B | A | Push-pull driving | 4.4 | | 4.5 | | 4.7 | | ns |
| | | | Open-drain driving | 1.9 | 5.3 | 1.1 | 4.4 | 1.2 | 4 | |
| t_{PLH} | | | Push-pull driving | 5.3 | | 4.5 | | 0.5 | | |
| | | | Open-drain driving | 45 | 175 | 36 | 140 | 27 | 102 | |
| t_{en} | OE | A or B | 200 | | 200 | | 200 | | ns | |
| t_{dis} | OE | A or B | 50 | | 40 | | 35 | | ns | |
| t_{rA} | A-port rise time | | Push-pull driving | 3.2 | 9.5 | 2.3 | 9.3 | 2 | 7.6 | ns |
| | | | Open-drain driving | 38 | 165 | 30 | 132 | 22 | 95 | |
| t_{rB} | B-port rise time | | Push-pull driving | 4 | 10.8 | 2.7 | 9.1 | 2.7 | 7.6 | ns |
| | | | Open-drain driving | 34 | 145 | 23 | 106 | 10 | 58 | |
| t_{fA} | A-port fall time | | Push-pull driving | 2 | 5.9 | 1.9 | 6 | 1.7 | 13.3 | ns |
| | | | Open-drain driving | 4.4 | 6.9 | 4.3 | 6.4 | 4.2 | 6.1 | |
| t_{fB} | B-port fall time | | Push-pull driving | 2.9 | 13.8 | 2.8 | 16.2 | 2.8 | 16.2 | ns |
| | | | Open-drain driving | 6.9 | 13.8 | 7.5 | 16.2 | 7 | 16.2 | |
| $t_{SK(O)}$ | Channel-to-channel skew | | 0.7 | | 0.7 | | 0.7 | | ns | |
| Max data rate | | | Push-pull driving | 21 | | 22 | | 24 | | Mbps |
| | | | Open-drain driving | 1 | | 1 | | 1 | | |

Switching Characteristics

 over recommended operating free-air temperature range, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | $V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ | | $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ | | $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$ | | UNIT |
|---------------|-------------------------|----------------|--------------------|---|-----|---|-----|---|------|------|
| | | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{PHL} | A | B | Push-pull driving | 3.2 | | 3.7 | | 3.8 | | ns |
| | | | Open-drain driving | 1.7 | 6.3 | 2 | 6 | 2.1 | 5.8 | |
| t_{PLH} | | | Push-pull driving | 3.5 | | 4.1 | | 4.4 | | |
| | | | Open-drain driving | 43 | 250 | 36 | 206 | 27 | 190 | |
| t_{PHL} | B | A | Push-pull driving | 3 | | 3.6 | | 4.3 | | ns |
| | | | Open-drain driving | 1.8 | 4.7 | 2.6 | 4.2 | 1.2 | 4 | |
| t_{PLH} | | | Push-pull driving | 2.5 | | 1.6 | | 1 | | |
| | | | Open-drain driving | 44 | 170 | 37 | 140 | 27 | 103 | |
| t_{en} | OE | A or B | | 200 | | 200 | | 200 | | ns |
| t_{dis} | OE | A or B | | 50 | | 40 | | 35 | | ns |
| t_{rA} | A-port rise time | | Push-pull driving | 2.8 | 7.4 | 2.6 | 6.6 | 1.8 | 5.6 | ns |
| | | | Open-drain driving | 34 | 149 | 28 | 121 | 24 | 89 | |
| t_{rB} | B-port rise time | | Push-pull driving | 3.2 | 8.3 | 2.9 | 7.2 | 2.4 | 6.1 | ns |
| | | | Open-drain driving | 35 | 151 | 24 | 112 | 12 | 64 | |
| t_{fA} | A-port fall time | | Push-pull driving | 1.9 | 5.7 | 1.9 | 5.5 | 1.8 | 5.3 | ns |
| | | | Open-drain driving | 4.4 | 6.9 | 4.3 | 6.2 | 4.2 | 5.8 | |
| t_{fB} | B-port fall time | | Push-pull driving | 2.2 | 7.8 | 2.4 | 6.7 | 2.6 | 6.6 | ns |
| | | | Open-drain driving | 5.1 | 8.8 | 5.4 | 9.4 | 5.4 | 10.4 | |
| $t_{SK(O)}$ | Channel-to-channel skew | | | 0.7 | | 0.7 | | 0.7 | | ns |
| Max data rate | | | Push-pull driving | 20 | | 22 | | 24 | | Mbps |
| | | | Open-drain driving | 1 | | 1 | | 1 | | |

TXS0102

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Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ | | $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$ | | UNIT |
|---------------|-------------------------|----------------|--------------------|---|-----|---|-----|------|
| | | | | MIN | MAX | MIN | MAX | |
| t_{PHL} | A | B | Push-pull driving | 2.4 | | 3.1 | | ns |
| | | | Open-drain driving | 1.3 | 4.2 | 1.4 | 4.6 | |
| t_{PLH} | | | Push-pull driving | 4.2 | | 4.4 | | |
| | | | Open-drain driving | 36 | 204 | 28 | 165 | |
| t_{PHL} | B | A | Push-pull driving | 2.5 | | 3.3 | | ns |
| | | | Open-drain driving | 1 | 124 | 1 | 97 | |
| t_{PLH} | | | Push-pull driving | 2.5 | | 2.6 | | |
| | | | Open-drain driving | 3 | 139 | 3 | 105 | |
| t_{en} | OE | A or B | | 200 | | 200 | | ns |
| t_{dis} | OE | A or B | | 40 | | 35 | | ns |
| t_{rA} | A-port rise time | | Push-pull driving | 2.3 | 5.6 | 1.9 | 4.8 | ns |
| | | | Open-drain driving | 25 | 116 | 19 | 85 | |
| t_{rB} | B-port rise time | | Push-pull driving | 2.5 | 6.4 | 2.1 | 7.4 | ns |
| | | | Open-drain driving | 26 | 116 | 14 | 72 | |
| t_{fA} | A-port fall time | | Push-pull driving | 2 | 5.4 | 1.9 | 5 | ns |
| | | | Open-drain driving | 4.3 | 6.1 | 4.2 | 5.7 | |
| t_{fB} | B-port fall time | | Push-pull driving | 2.3 | 7.4 | 2.4 | 7.6 | ns |
| | | | Open-drain driving | 5 | 7.6 | 4.8 | 8.3 | |
| $t_{SK(O)}$ | Channel-to-channel skew | | | 0.7 | | 0.7 | | ns |
| Max data rate | | | Push-pull driving | 23 | | 24 | | Mbps |
| | | | Open-drain driving | 1 | | 1 | | |

PRINCIPLES OF OPERATION

Applications

The TXS0102 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0102 is ideal for use in applications where an open-drain driver is connected to the data I/Os. The TXS0102 can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0102 might be a better option for such push-pull applications.

Architecture

The TXS0102 architecture (see [Figure 1](#)) does not require a direction-control signal to control the direction of data flow from A to B or from B to A.

PRINCIPLES OF OPERATION (continued)

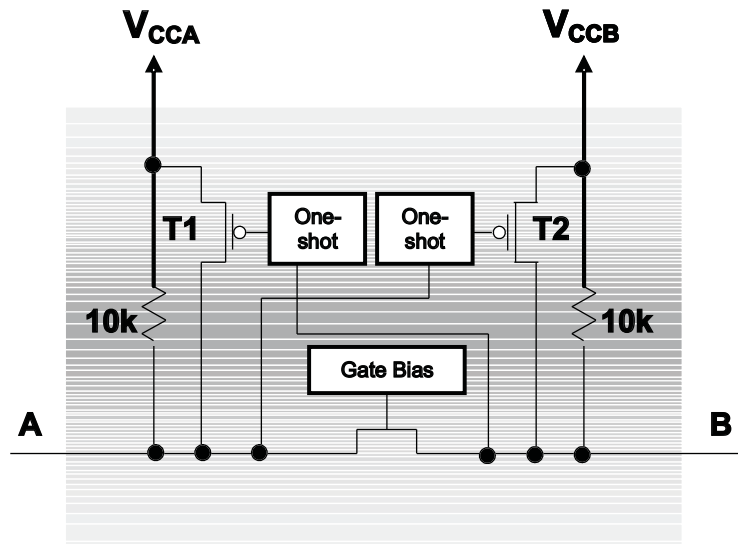


Figure 1. Architecture of a TXS01xx Cell

Each A-port I/O has an internal 10-k Ω pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-k Ω pullup resistor to V_{CCB} . The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1,T2) for a short duration, which speeds up the low-to-high transition.

Input Driver Requirements

The fall time (t_{fA} , t_{fB}) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0102. Similarly, the t_{PHL} and max data rates also depend on the output impedance of the external driver. The values for t_{fA} , t_{fB} , t_{PHL} , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50 Ω .

Power Up

During operation, ensure that $V_{CCA} \leq V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \geq V_{CCB}$ does not damage the device, so any power supply can be ramped up first.

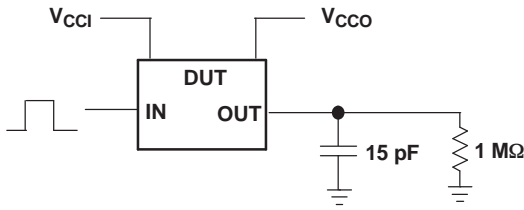
Enable and Disable

The TXS0102 has an OE input that is used to disable the device by setting OE low, which places all I/Os in the Hi-Z state. The disable time (t_{dis}) indicates the delay between the time when OE goes low and when the outputs actually get disabled (Hi-Z). The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

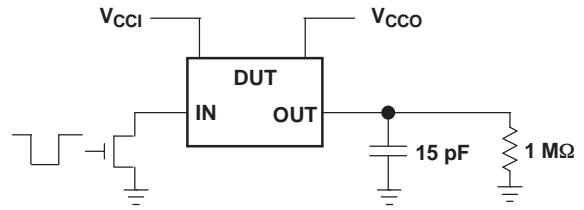
Pullup or Pulldown Resistors on I/O Lines

Each A-port I/O has an internal 10-k Ω pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-k Ω pullup resistor to V_{CCB} . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to V_{CCA} or V_{CCB} (in parallel with the internal 10-k Ω resistors).

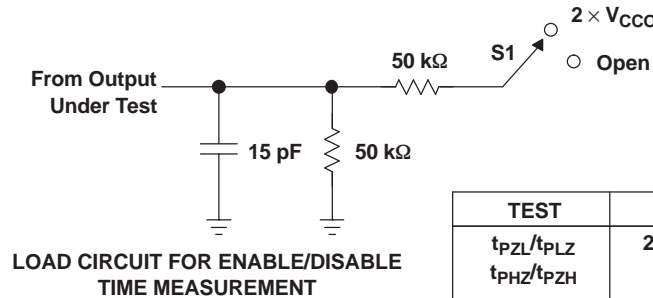
PARAMETER MEASUREMENT INFORMATION



DATA RATE, PULSE DURATION, PROPAGATION DELAY, OUTPUT RISE AND FALL TIME MEASUREMENT USING A PUSH-PULL DRIVER

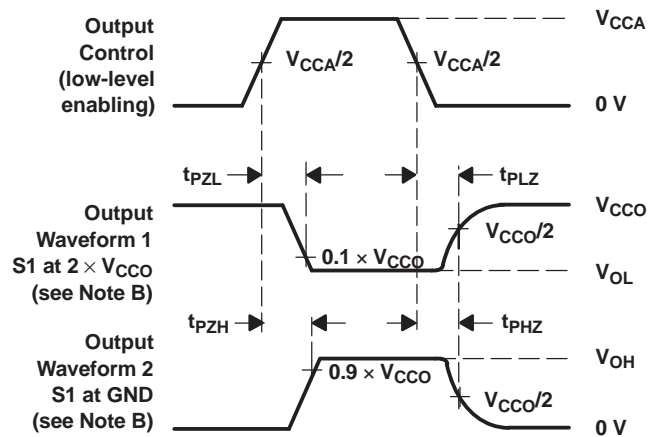
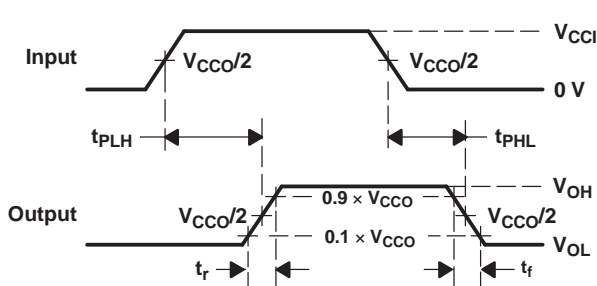
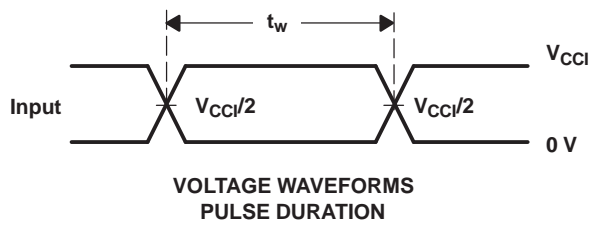


DATA RATE, PULSE DURATION, PROPAGATION DELAY, OUTPUT RISE AND FALL TIME MEASUREMENT USING AN OPEN-DRAIN DRIVER



LOAD CIRCUIT FOR ENABLE/DISABLE TIME MEASUREMENT

| TEST | S1 |
|-------------------|--------------------|
| t_{PZL}/t_{PLZ} | $2 \times V_{CCO}$ |
| t_{PHZ}/t_{PZH} | Open |



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1$ V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - V_{CCI} is the V_{CC} associated with the input port.
 - V_{CCO} is the V_{CC} associated with the output port.
 - All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| TXS0102DCUR | ACTIVE | US8 | DCU | 8 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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